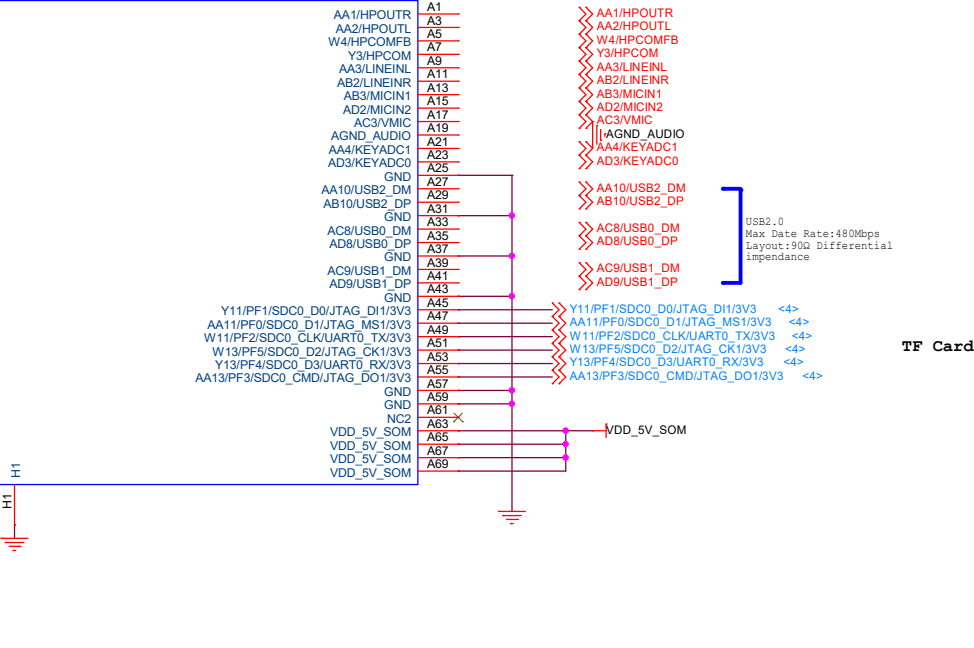
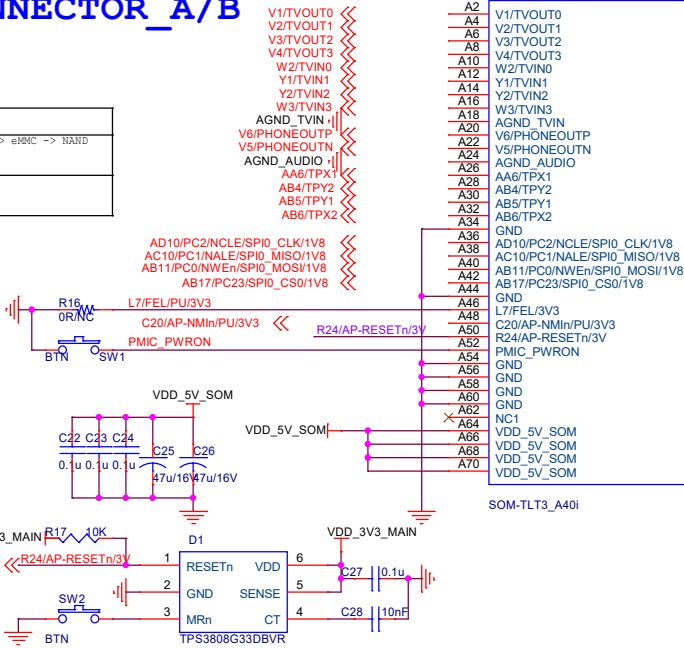


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SOM_CONNECTOR_A/B

L7/FEL	BOOT DEVICE
1	Micro SD-> SPI NOR -> eMMC -> NAND 已内部上拉
0	J8B0



MIPI DSI
Max Data Rate:1Gbps
Layout:100Q Differential
impedance

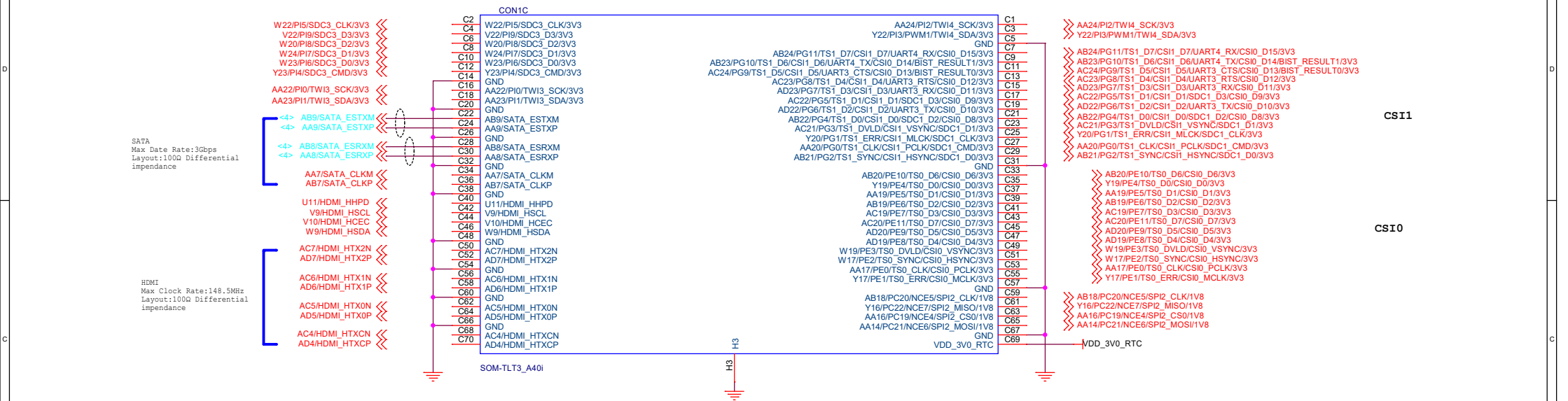
LVDS0
Max Clock Rate:75MHz
Layout:100Q Differential
impedance

ETH1 1000M

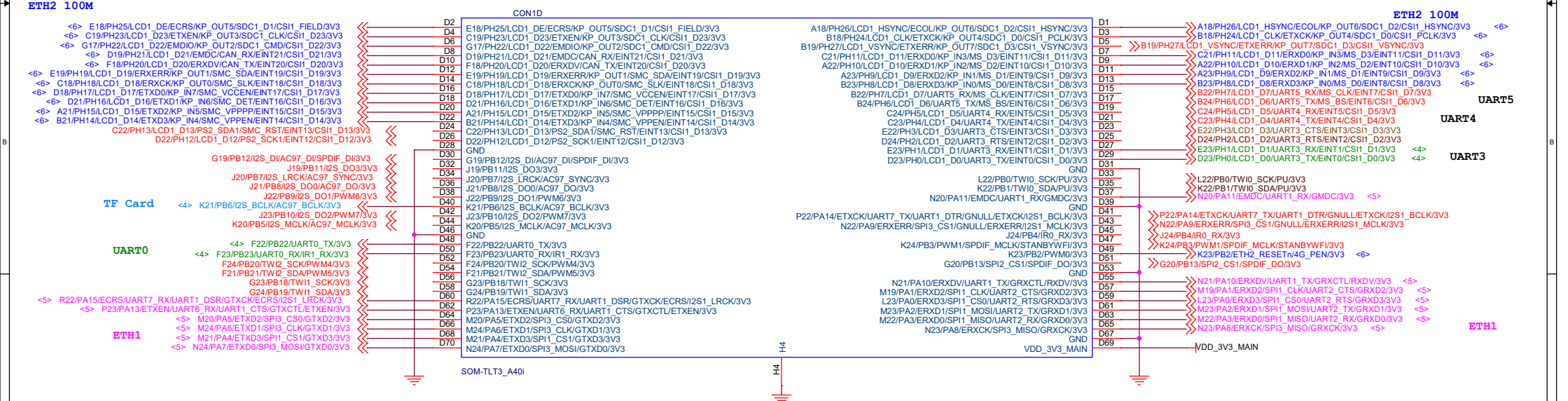
LVDS0
Max Clock Rate:75MHz
Layout:100Q Differential
impedance

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SOM CONNECTOR C/D



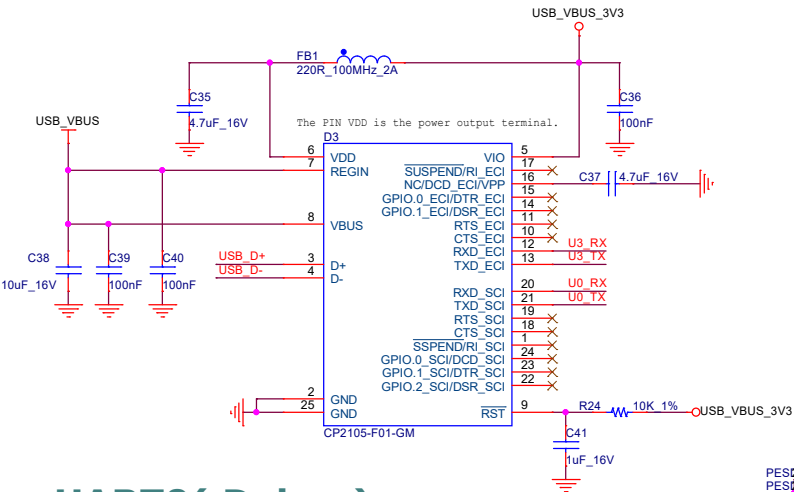
ETH2 100M



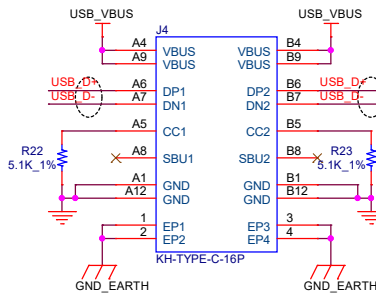
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<3> D23/PH0/LCD1_D0/UART3_TX/EINT0/CSI1_D0/3V3
<3> E23/PH1/LCD1_D1/UART3_RX/EINT1/CSI1_D1/3V3
<3> F22/PB22/UART0_TX/3V3
<3> F23/PB23/UART0_RX/IR1_RX/3V3

DNP



UART0(Debug)

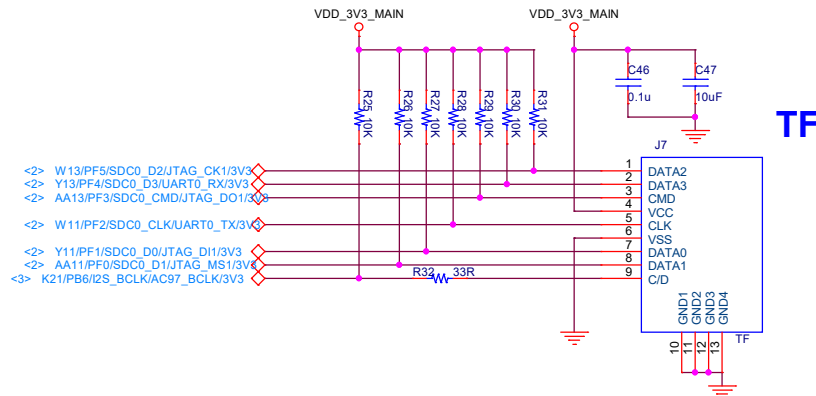
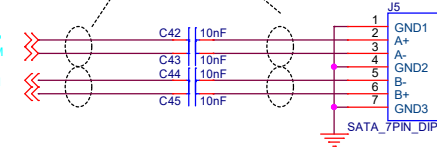


SATA

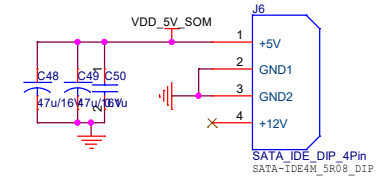
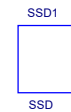
<3> AA9/SATA_ESTXP
<3> AB9/SATA_ESTXM
<3> AB8/SATA_ESRXM
<3> AA8/SATA_ESRXP

Signal pairs routing with 100 ohm differential impedance

Maximum Speed :3Gbps

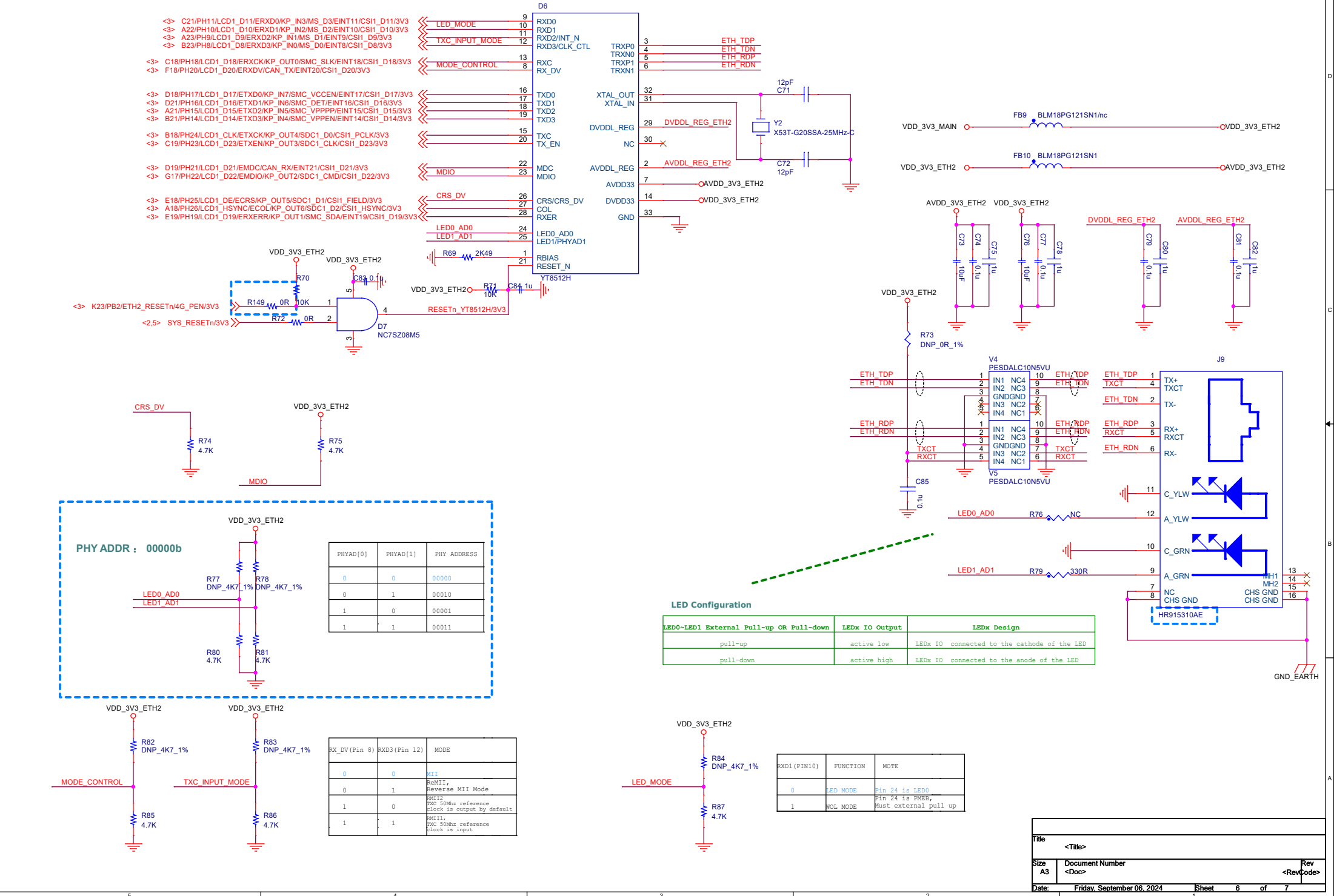


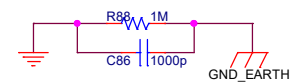
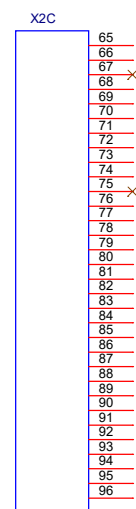
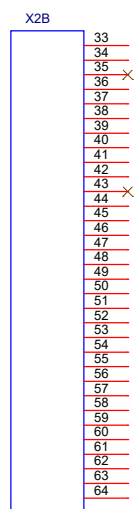
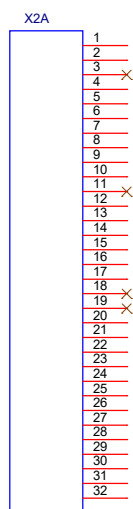
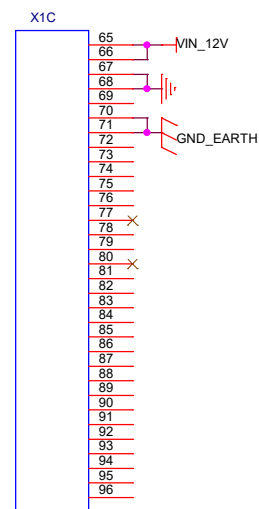
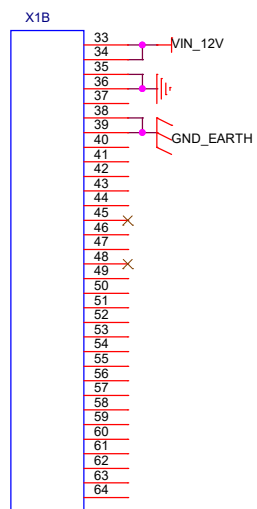
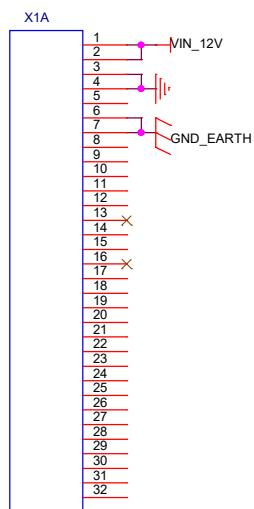
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ETH2 (MII ,10M/100Mbps)





x1放在顶层右侧
x2放在顶层左侧

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